



Material Content Data Sheet



Sales Product Name				IPB083N10N3 G		Issued		20. July 2018	
MA#				MA001278508					
Package				PG-TO263-3-2		Weight*		1559.66 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	4.609	0.30	0.30	2955	2955	
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		195		
	inorganic material	phosphorus	7723-14-0	0.091	0.01		59		
	non noble metal	copper	7440-50-8	304.026	19.49	19.52	194932	195186	
wire	non noble metal	aluminium	7429-90-5	6.201	0.40	0.40	3976	3976	
encapsulation	organic material	carbon black	1333-86-4	10.236	0.66		6563		
	plastics	epoxy resin	-	112.594	7.22		72192		
	inorganic material	silicondioxide	60676-86-0	559.560	35.87	43.75	358771	437526	
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6192	6192	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		146		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	358770	146	
solder	noble metal	silver	7440-22-4	0.094	0.01		60		
	non noble metal	tin	7440-31-5	0.075	0.00		48		
	non noble metal	lead	7439-92-1	3.600	0.23	0.24	2308	2416	
heatspreader	non noble metal	iron	7439-89-6	0.548	0.04		352		
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105		
	non noble metal	copper	7440-50-8	547.666	35.11	35.16	351146	351603	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com